

AMENDMENTS TO THE CLAIMS

Please amend the Claims as follows. Insertions are shown underlined while deletions are ~~struck through~~.

1 (currently amended): A dicing/die-bonding film comprising a pressure-sensitive adhesive layer on a supporting base material and a die-bonding adhesive layer on the pressure-sensitive adhesive layer,

wherein ~~releasability in~~ an interface between the pressure-sensitive adhesive layer and the die-bonding adhesive layer ~~is different between~~ comprises an interface (A) corresponding to a work-attaching region in the die-bonding adhesive layer and an interface (B) corresponding to a part or a whole of a region other than the work-attaching region, and ~~the releasability between the pressure-sensitive adhesive layer and the die-bonding adhesive layer~~ of at the interface (A) is higher than the releasability ~~of~~ at the interface (B).

2 (previously presented): The dicing/die-bonding film according to claim 1, wherein adhesion of the pressure-sensitive adhesive layer to the die-bonding adhesive layer is different between a region (a) corresponding to the work-attaching region in the die-bonding adhesive layer and a region (b) corresponding to a part or the whole of the other region, and satisfies the relationship:

the adhesion of the region (a) is lower than the adhesion of region (b).

3 (previously presented): The dicing/die-bonding film according to claim 1, wherein adhesion of the work-attaching region in the die-bonding adhesive layer to a work and to the region (a) satisfies the relationship:

the adhesion to the work is higher than the adhesion to the region (a).

4 (previously presented): The dicing/die-bonding film according to claim 1, wherein the part of the region other than the work-attaching region in the die-bonding adhesive layer is a dicing ring-attaching region.

5 (previously presented): The dicing/die-bonding film according to claim 4, wherein adhesion of the dicing ring-attaching region in the die-bonding adhesive layer to a dicing ring and to a region (b') corresponding to the dicing ring-attaching region satisfies the relationship:

the adhesion to the dicing ring is lower than the adhesion to the region (b').

6 (withdrawn): A dicing/die-bonding film comprising a pressure-sensitive adhesive layer on a supporting base material and a die-bonding adhesive layer on the pressure-sensitive adhesive layer,

wherein the die-bonding adhesive layer is arranged as a work-attaching region on a part of the pressure-sensitive adhesive layer, and

a region (a) corresponding to the work-attaching region in the pressure sensitive adhesive layer and a region (b) other than the region (a) are different in adhesion and satisfy the relationship:

the adhesion of the region (a) is lower than the region (b).

7 (withdrawn): The dicing/die-bonding film according to claim 6, wherein adhesion of the work-attaching region to the work and to the region (a) satisfies the relationship:

the adhesion to the work is higher than the adhesion to the region (a).

8 (previously presented): The dicing/die-bonding film according to claim 1, wherein the pressure-sensitive adhesive layer is made of a radiation-curing pressure-sensitive adhesive, and the region (a) corresponding to the work-attaching region is irradiated with radiations.

9 (withdrawn): The dicing/die-bonding film according to claim 6, wherein the pressure-sensitive adhesive layer is made of a radiation-curing pressure-sensitive adhesive, and the region (a) corresponding to the work-attaching region is irradiated with radiations.

10 (withdrawn): A method of fixing a chipped work, comprising the steps of:

pressing a work onto the work-attaching region of the die-bonding adhesive layer in the dicing/die-bonding film described in claim 1,

dicing the work into chips,

releasing the chipped work together with the work-attaching region of the die-bonding adhesive layer from a region (a) of the pressure-sensitive adhesive layer corresponding to the work-attaching region, and

fixing the chipped work to a semiconductor element via the work-attaching region of the die-bonding adhesive layer.

11 (withdrawn): A semiconductor device comprising a chipped work fixed onto a semiconductor element via the work-attaching region of the die-bonding adhesive layer by the method of fixing a chipped work as described in claim 10.

12 (withdrawn): A method of fixing a chipped work, comprising the steps of:

pressing a work onto the work-attaching region of the die-bonding adhesive layer in the dicing/die-bonding film set forth in claim 6,

dicing the work into chips,

releasing the chipped work together with the work-attaching region of the die-bonding adhesive layer from the region (a) of the pressure-sensitive adhesive layer, and

fixing the chipped work to a semiconductor element via the work-attaching region of the die-bonding adhesive layer.

13 (withdrawn): The method according to claim 10, wherein the pressure-sensitive adhesive layer is made of a radiation-curing pressure-sensitive adhesive, and the region (a) is irradiated with radiations.

14 (withdrawn): The method according to claim 12, wherein the pressure-sensitive adhesive layer is made of a radiation-curing pressure-sensitive adhesive, and the region (a) is irradiated with radiations.